

# Cascadable Silicon Bipolar MMIC Amplifier

Electrostatic sensitive device. Observe precautions for handling.



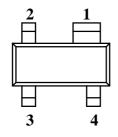
## **Applications**

General purpose 50  $\Omega$  gain block for narrow and broad band IF and RF amplifiers in commercial and industrial applications. The 50  $\Omega$  level allows directly to cascade

this amplifier with minimal external circuitry, thus providing a simple, cost effective way to achieve low level amplification.

#### **Features**

- Broadband amplification
- Low operating voltage (6 V)
- $50 \Omega$  cascadable gain block
- High gain (17.5 dB at 900 MHz)



- Low noise figure (3.3 dB at 900 MHz)
- Low cost surface mount plastic package
- Few external components

94 9279

S858TA3 Marking: TA3 Plastic case (SOT 143)

1 = RF-output; 2 = Ground; 3 = RF-input; 4 = Ground

## **Absolute Maximum Ratings**

Parameters	Symbol	Value	Unit
Device current	I <sub>bias</sub>	35	mA
RF input power	P <sub>in</sub>	+20	dBm
Total power dissipation $T_{amb} \le 60^{\circ}C$	P <sub>tot</sub>	200	mW
Junction temperature	Tj	150	°C
Storage temperature range	T <sub>stg</sub>	-65 to +150	°C

#### **Maximum Thermal Resistance**

Parameters	Symbol	Value	Unit
Channel ambient on glass fibre printed board			
(25 x 20 x 1.5) mm <sup>3</sup> plated with 35 μm Cu	$R_{thJA}$	450	K/W

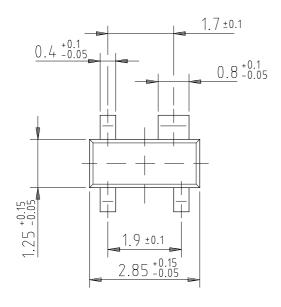


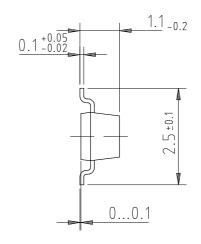
## **Electrical AC Characteristics**

 $T_{amb} = 25$ °C,  $I_{bias} = 29$  mA,  $Z_0 = 50$   $\Omega$ , f = 900 MHz

Parameters / Test Conditions	Symbol	Min.	Typ.	Max.	Unit
Power gain	$G_p$	17	17.5		dB
3 dB bandwidth	f <sub>3dB</sub>		500		MHz
Input VSWR f = 0.1 to 2.5 GHz	VSWR		1.8:1		
Output VSWR f = 0.1 to 2.5 GHz	VSWR		1.8:1		
Noise figure f = 900 MHz	F		3.3		dB
Intermodulation distortion 22.5 mV input voltage	IM <sub>3</sub>		50		dB
1 dB compression point	P <sub>1dB</sub>		10		dBm
Device voltage	$V_d$	2.9	3.6	4.3	V

## **Dimensions in mm**





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96 12240

technical drawings according to DIN specifications



### **Ozone Depleting Substances Policy Statement**

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

- 1. Meet all present and future national and international statutory requirements.
- Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**TEMIC TELEFUNKEN microelectronic GmbH** semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**TEMIC** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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